

Ultra Micronized Dicyandiamide

CAS NO. 461-58-5

DESCRIPTION

Ultra micronized Dicyandiamide is a curing agent containing 1.5% of an inert flow control additive to inhibit clumping and improve handling. It is designed for use as a latent curing agent for epoxy resins.

ADVANTAGES

Fine particle size provides enhanced reactivity versus coarser grades

Easily dispersed in liquid resins

Shelf stability up to 6 months at 25°C in properly formulated systems

Activation temperature can be easily varied from 180°C to 95°C with appropriate accelerator selection

STORAGE LIFE

At least 12 months from the date of manufacture in the original sealed container at ambient temperature. Store away from excessive heat and humidity in tightly closed containers.

HEALTH & SAFETY PRECAUTIONS

Ultra Micronized Dicyandiamide is not flammable, corrosive or explosive. Dicyandiamide will decompose slowly above 80°C in water to generate ammonia, so material should be kept dry and away from steam pipes or excessively hot areas. While Ultra Micronized Dicy is not a primary skin or eye irritant, epoxy resins in which it is used can produce irritation. Removal with soap and water is sufficient. Avoid using solvents as these can dry the skin and increase the irritation potential of epoxy resins.

APPLICATIONS

One Component Adhesives

Epoxy Powder Coatings

Prepregs and Film Adhesives

Electronic Potting and Encapsulating Compounds

TY PICAL PROPERTIES

Appearance	Free Flowing White powder
Melt Point (°C)	209-212
Purity[%]	>98
Free Water (%)	<0.3
Particle Size (98%) [μm]	<10
Heat Distortion Temperature (°C)	125